

Title (en)

METHOD AND CAST PART PRODUCTION SYSTEM FOR PRODUCING AN ELECTRIC MOTOR HOUSING, AND ELECTRIC MOTOR

Title (de)

VERFAHREN UND GUSSTEILHERSTELLUNGSANLAGE ZUM HERSTELLEN EINES ELEKTROMOTOR-GEHÄUSES UND ELEKTROMOTOR

Title (fr)

PROCÉDÉ ET SYSTÈME DE PRODUCTION DE PIÈCE COULÉE POUR LA PRODUCTION D'UN CARTER DE MOTEUR ÉLECTRIQUE, ET MOTEUR ÉLECTRIQUE

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Application

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Abstract (en)

[origin: WO2022053397A1] The invention relates to a printed circuit board (10), comprising a top side (11) for receiving electrical components (55), a bottom side (12) for receiving a heat sink (50), a plurality of electrically conductive layers (40) and a plurality of electrically insulating insulation layers (31, 32, 33, 34, 35), wherein a main insulation layer (31) is arranged between the top side (11) and the bottom side (12), wherein the main insulation layer (31) completely electrically insulates electrically conductive layers (40) which are arranged between the main insulation layer (31) and the top side (11) from electrically conductive layers (40) which are arranged between the main insulation layer (31) and the bottom side (12), and wherein a plurality of upper plated-through holes (21) extend at least from an outer insulation layer (33), which is adjacent to the top side (11), into an inner insulation layer (34), which is adjacent to the main insulation layer (31), and wherein a plurality of lower plated-through holes (22) extend at least from the bottom side (12) into a lower insulation layer (32), which is adjacent to the main insulation layer (31). The invention also relates to a circuit arrangement (15), comprising a printed circuit board according to the invention, a plurality of electrical components (55) which are fitted to the top side (11) of the printed circuit board and are connected to the printed circuit board (10), and at least one heat sink (50) which is fitted to the bottom side (12) of the printed circuit board and is connected to the printed circuit board (10).

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